



ORIENTAL
SEMICONDUCTOR

GreenMOS™

OSG60R1K8xF_Datasheet

Green
PRODUCT

RoHS
compliant

Enhancement Mode N-Channel Power MOSFET

Features

- ◆ Low $R_{DS(on)}$ & FOM
- ◆ Extremely low switching loss
- ◆ Excellent stability and uniformity
- ◆ Easy to drive

Applications

- ◆ Lighting
- ◆ Hard switching PWM
- ◆ Server power supply
- ◆ Charger

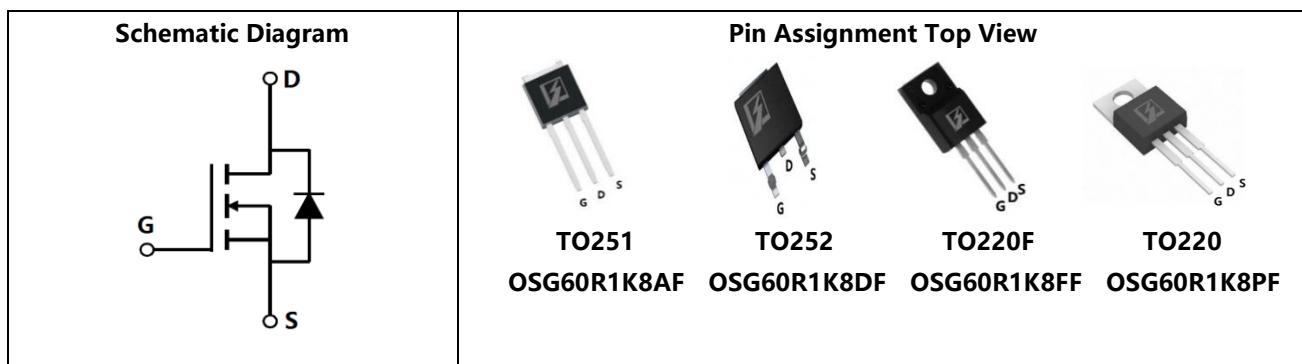


■ General Description

OSG60R1K8xF use advanced GreenMOS™ technology to provide low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. This device is suitable for active power factor correction and switching mode power supply applications.

◆ V_{DS} , min@ T_{jmax}	650 V
◆ I_D , pulse	9 A
◆ $R_{DS(ON)}$, max @ $V_{GS}=10$ V	1.8 Ω
◆ Q_g	7.0 nC

■ Schematic and Package Information



■ Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	600	V
Gate source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾ , $T_c=25^\circ\text{C}$	I_D	3	A
Continuous drain current ¹⁾ , $T_c=100^\circ\text{C}$		1.9	
Pulsed drain current ²⁾ , $T_c=25^\circ\text{C}$	$I_{D, \text{pulse}}$	9	A
Power dissipation ³⁾ for TO251, TO252, TO220, $T_c=25^\circ\text{C}$	P_D	22.3	W
Power dissipation ³⁾ for TO220F, $T_c=25^\circ\text{C}$		20	
Single pulsed avalanche energy ⁵⁾	E_{AS}	70	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0...480$ V	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0...480$ V, $I_{SD} \leq I_D$	dv/dt	15	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	°C



■ Thermal Characteristics

Parameter	Symbol	Value		Unit
		TO251/TO252/TO220	TO220F	
Thermal resistance, junction-case	R _{θJC}	5.6	6.3	°C/W
Thermal resistance, junction-ambient ⁴⁾	R _{θJA}	62	62.5	°C/W

■ Electrical Characteristics at T_j=25 °C unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV _{DSS}	600			V	V _{GS} =0 V, I _D =250 μA
		650	750			V _{GS} =0 V, I _D =250 μA, T _j =150 °C
Gate threshold voltage	V _{GS(th)}	2.0		4.0	V	V _{DS} =V _{GS} , I _D =250 μA
Drain-source on-state resistance	R _{DS(ON)}		1.5	1.8	Ω	V _{GS} =10 V, I _D =1 A
			3.34			V _{GS} =10 V, I _D =1 A, T _j =150 °C
Gate-source leakage current	I _{GSS}			100	nA	V _{GS} =30 V
				-100		V _{GS} =-30 V
Drain-source leakage current	I _{DSS}			1	μA	V _{DS} =600 V, V _{GS} =0 V

■ Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{iss}		175		pF	V _{GS} =0 V, V _{DS} =50 V, f=1 MHz
Output capacitance	C _{oss}		14		pF	
Reverse transfer capacitance	C _{rss}		0.86		pF	
Turn-on delay time	t _{d(on)}		18		ns	V _{GS} =10 V, V _{DS} =380 V, R _G =50 Ω, I _D =1 A
Rise time	t _r		6.6		ns	
Turn-off delay time	t _{d(off)}		90		ns	
Fall time	t _f		40		ns	



■ Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q_g		7.0		nC	$I_D=3\text{ A}$, $V_{DS}=480\text{ V}$, $V_{GS}=10\text{ V}$
Gate-source charge	Q_{gs}		1.4		nC	
Gate-drain charge	Q_{gd}		3.6		nC	
Gate plateau voltage	$V_{plateau}$		5.6		V	

■ Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward current	I_S			3	A	$V_{GS} < V_{th}$
Pulsed source current	I_{SP}			9		
Diode forward voltage	V_{SD}			1.3	V	$I_S=3\text{ A}, V_{GS}=0\text{ V}$
Reverse recovery time	t_{rr}		114		ns	$V_R=400\text{ V}, I_S=3\text{ A}$, $di/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	Q_{rr}		0.583		μC	
Peak reverse recovery current	I_{rrm}		8.5		A	

■ Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\text{ }^\circ\text{C}$.
- 5) $V_{DD}=50\text{ V}$, $R_G=25\text{ }\Omega$, $L=22.5\text{ mH}$, starting $T_j=25\text{ }^\circ\text{C}$.

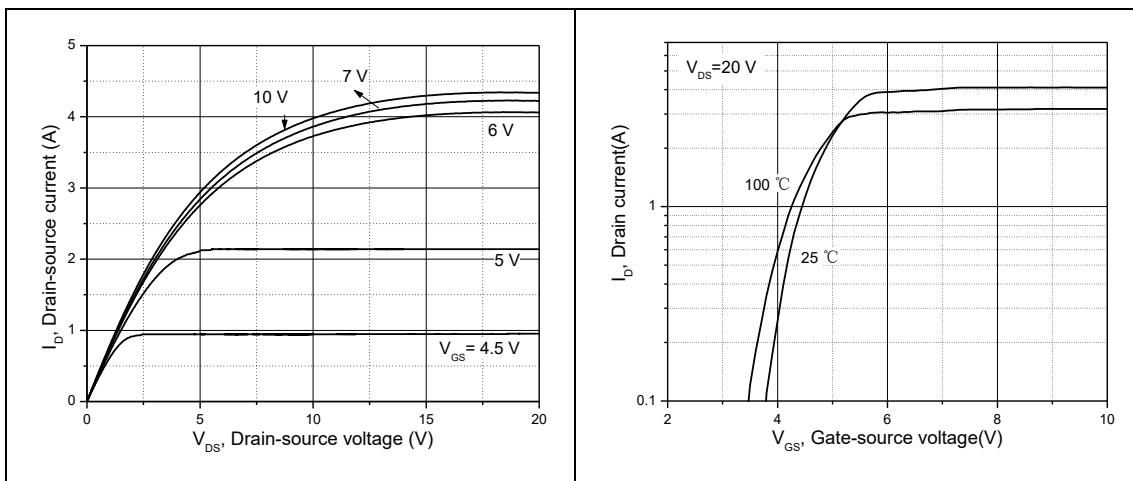
**■ Electrical Characteristics Diagrams**

Figure 1, Typ. output characteristics

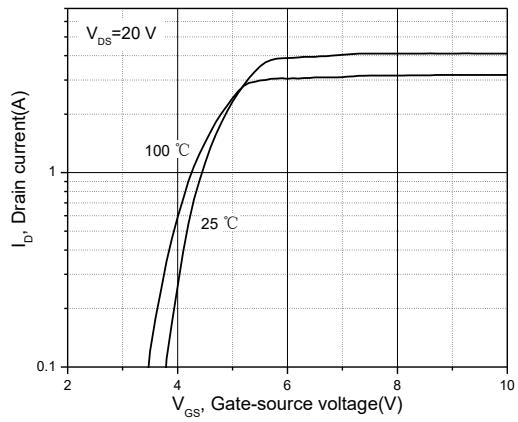


Figure 2, Typ. transfer characteristics

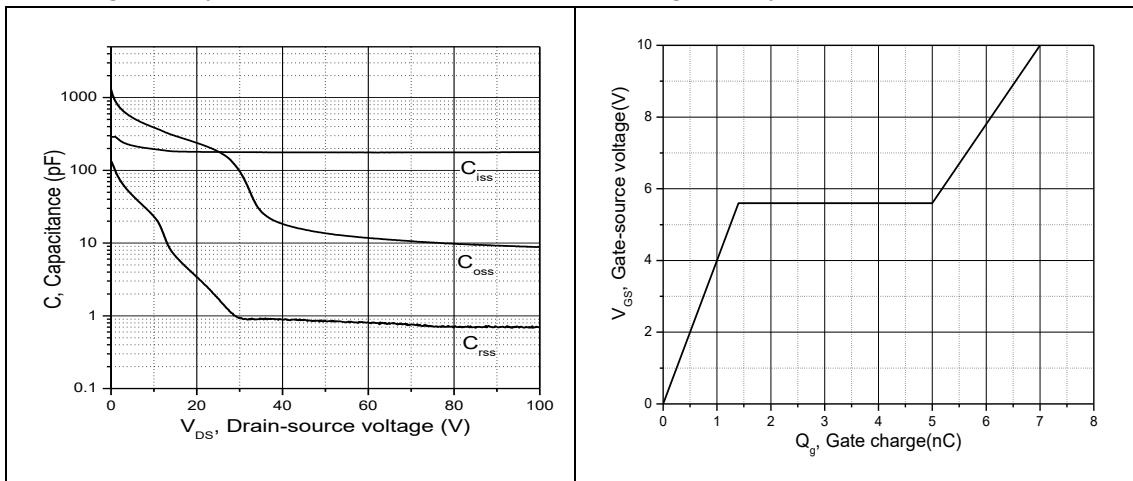


Figure 3, Typ. capacitances

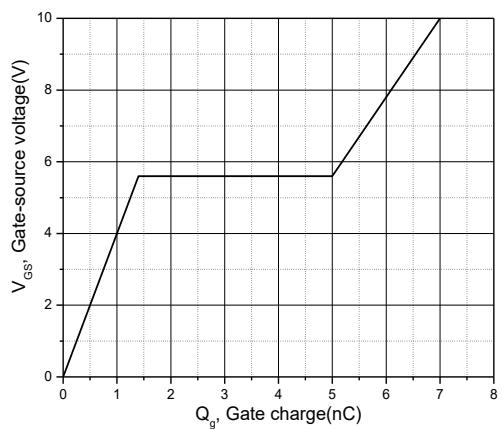


Figure 4, Typ. gate charge

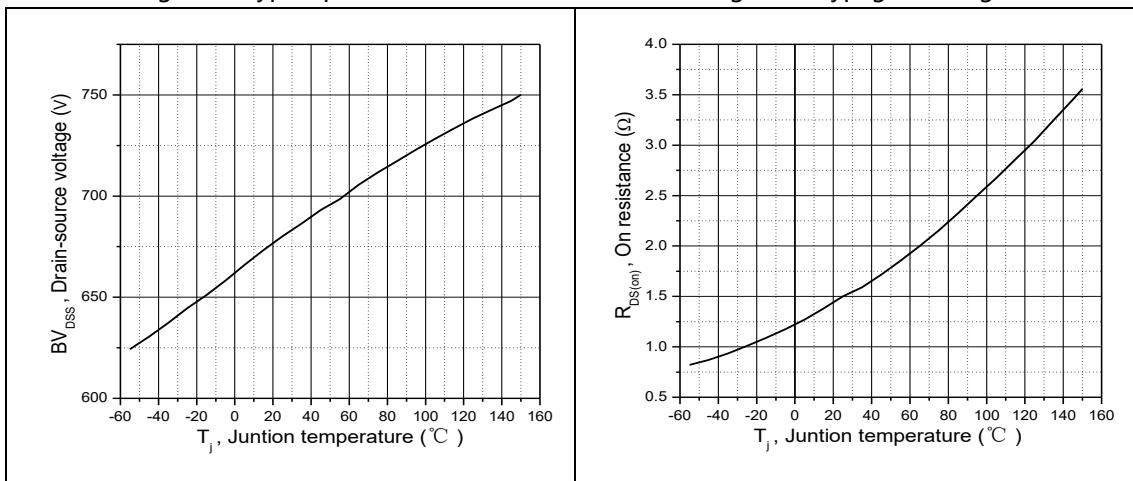


Figure 5, Drain-source breakdown voltage

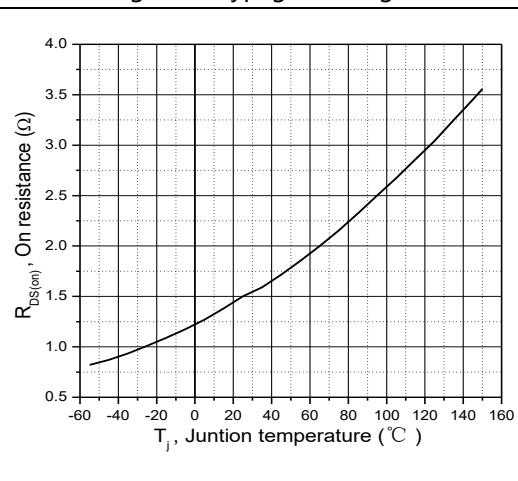


Figure 6, Drain-source on-state resistance

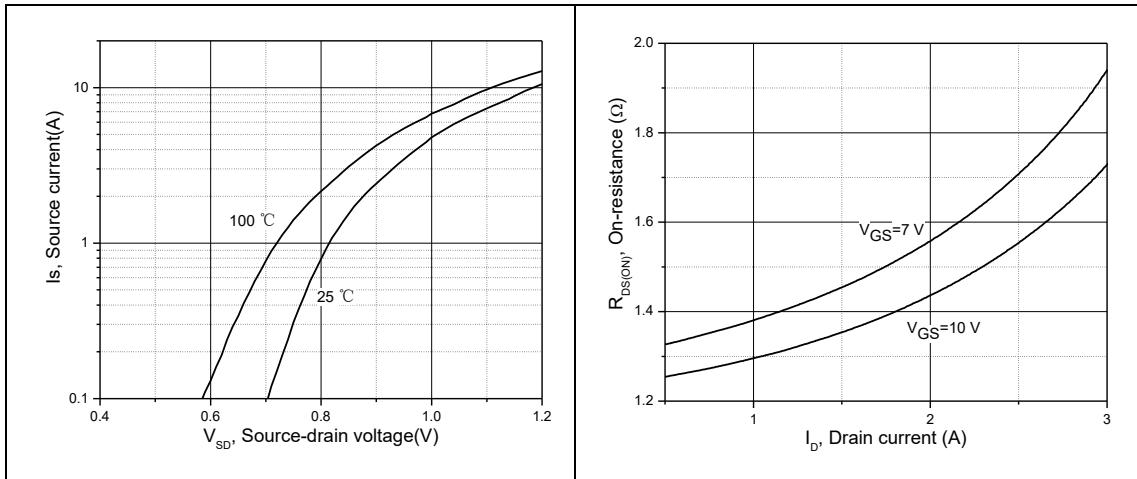


Figure 7, Forward characteristic of body diode

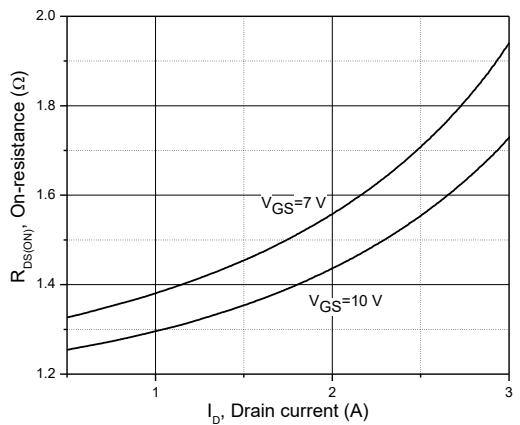


Figure 8, Drain-source on-state resistance

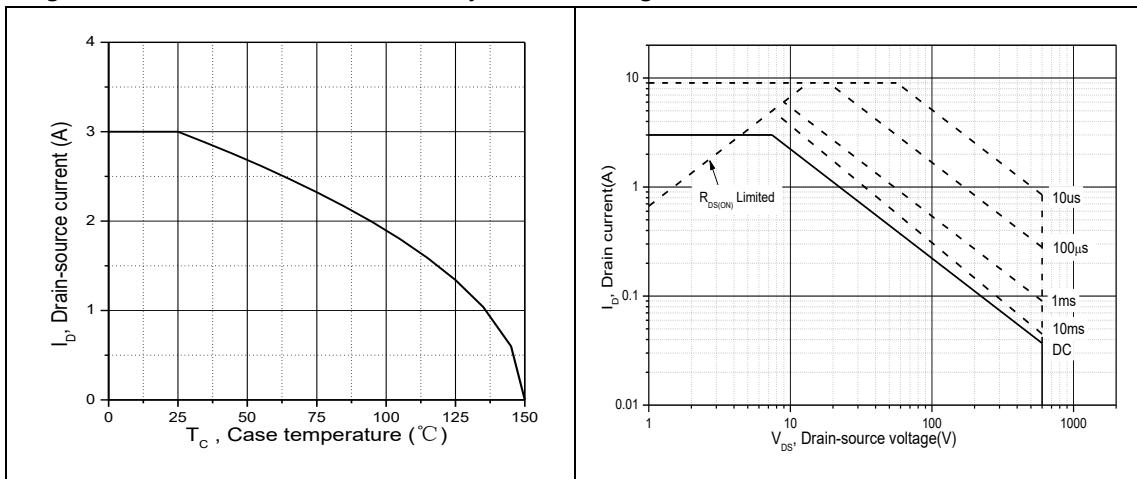
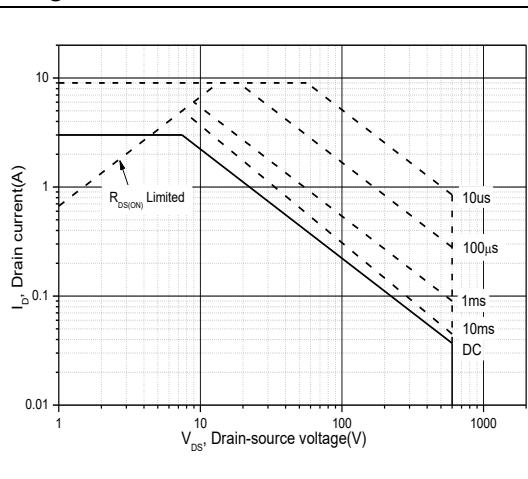
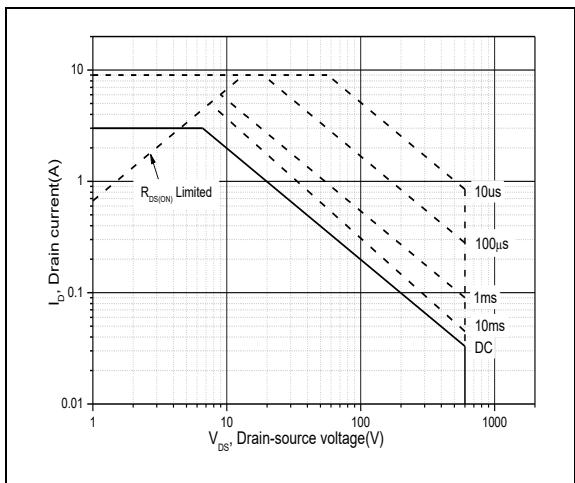


Figure 9, Drain current

Figure 10, Safe operation area for
TO251/TO252/TO220 $T_C=25^\circ\text{C}$ Figure 11, Safe operation area for TO220F
 $T_C=25^\circ\text{C}$

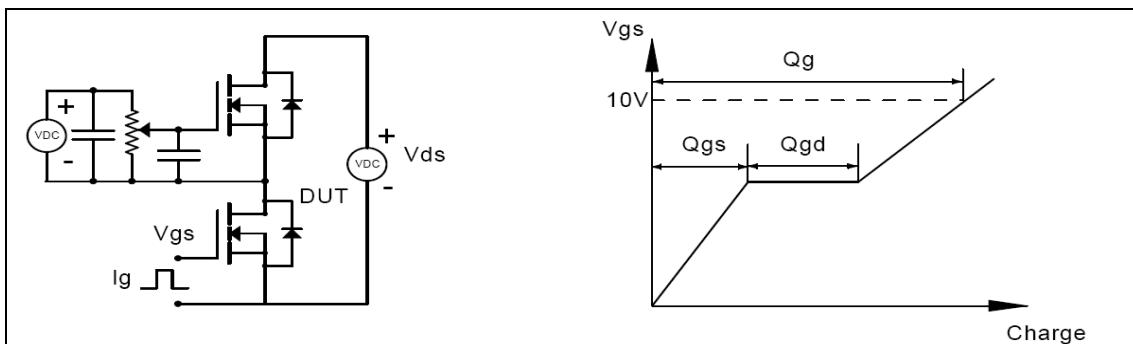
**■ Test circuits and waveforms**

Figure 1, Gate charge test circuit & waveform

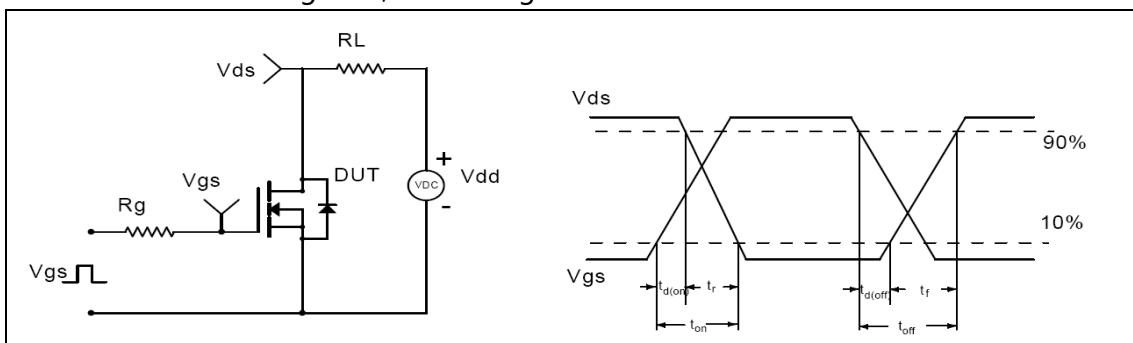


Figure 2, Switching time test circuit & waveforms

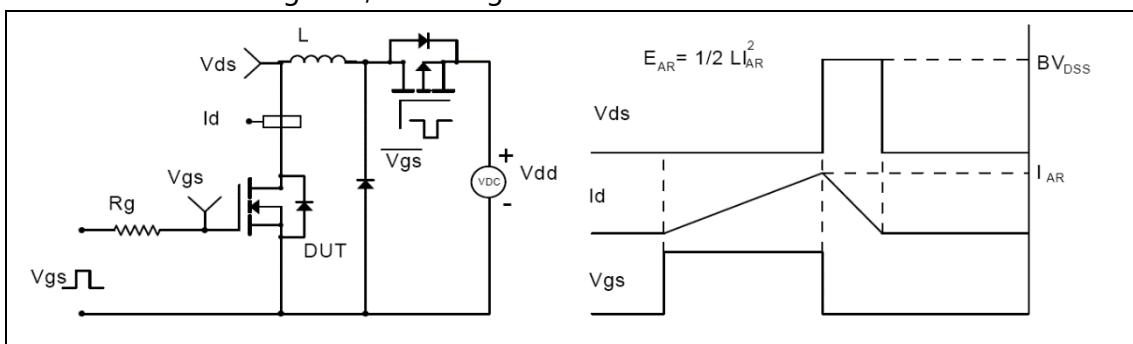


Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms

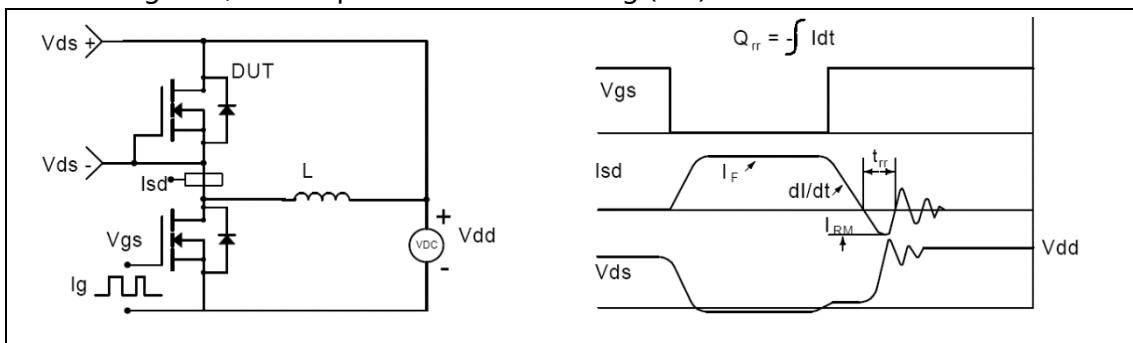
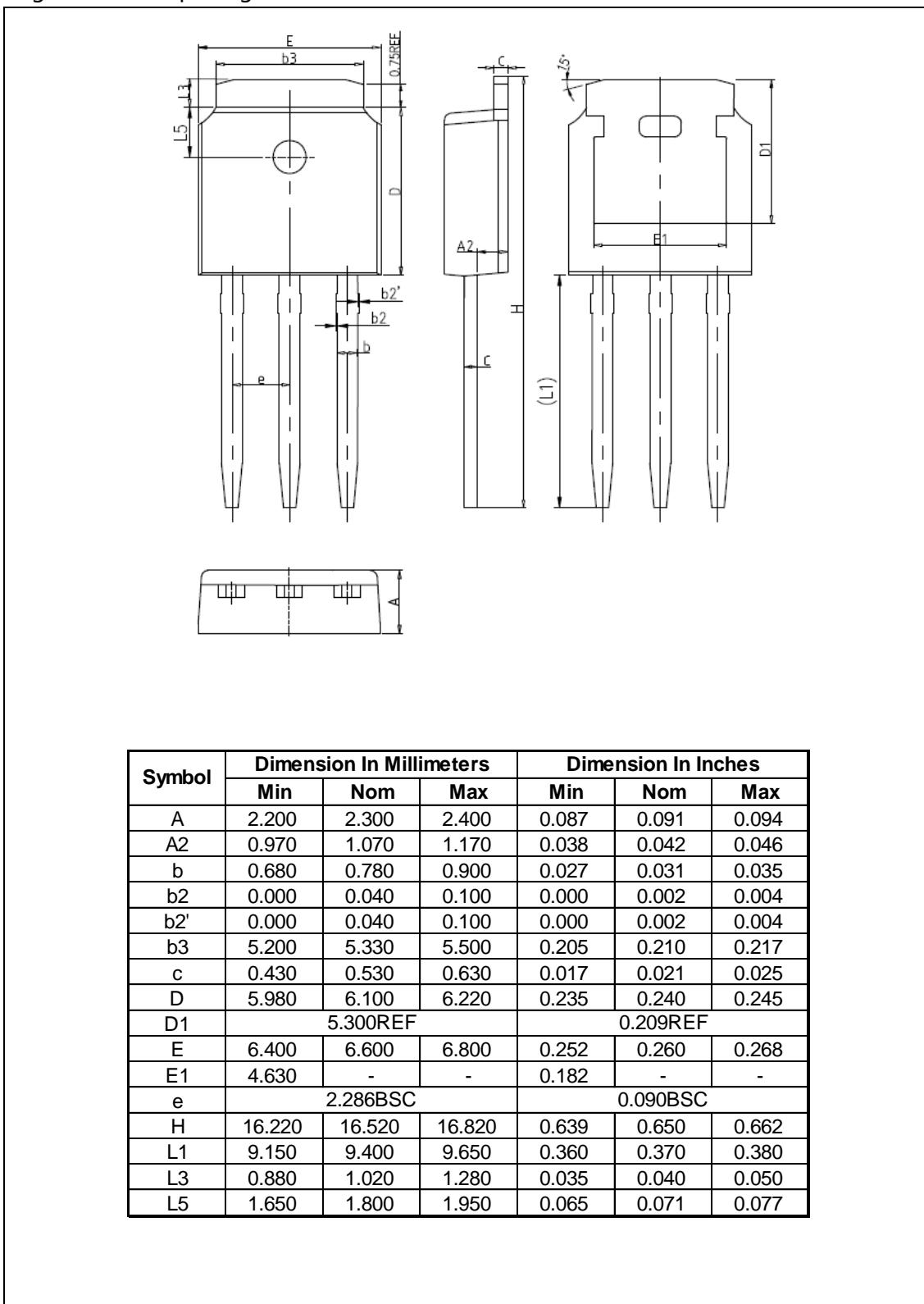


Figure 4, Diode reverse recovery test circuit & waveforms



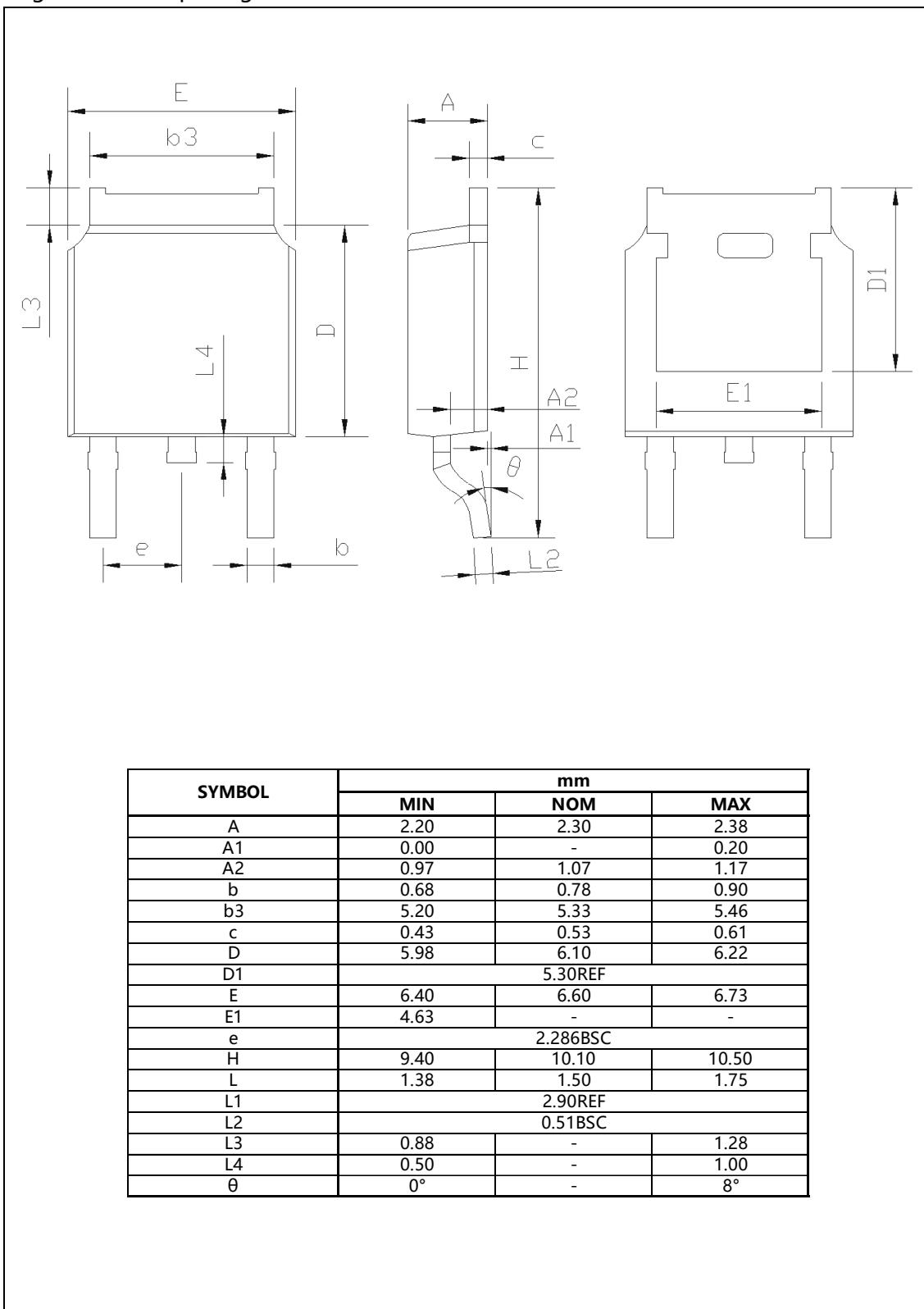
■ Package Information

Figure1, TO251 package outline dimension



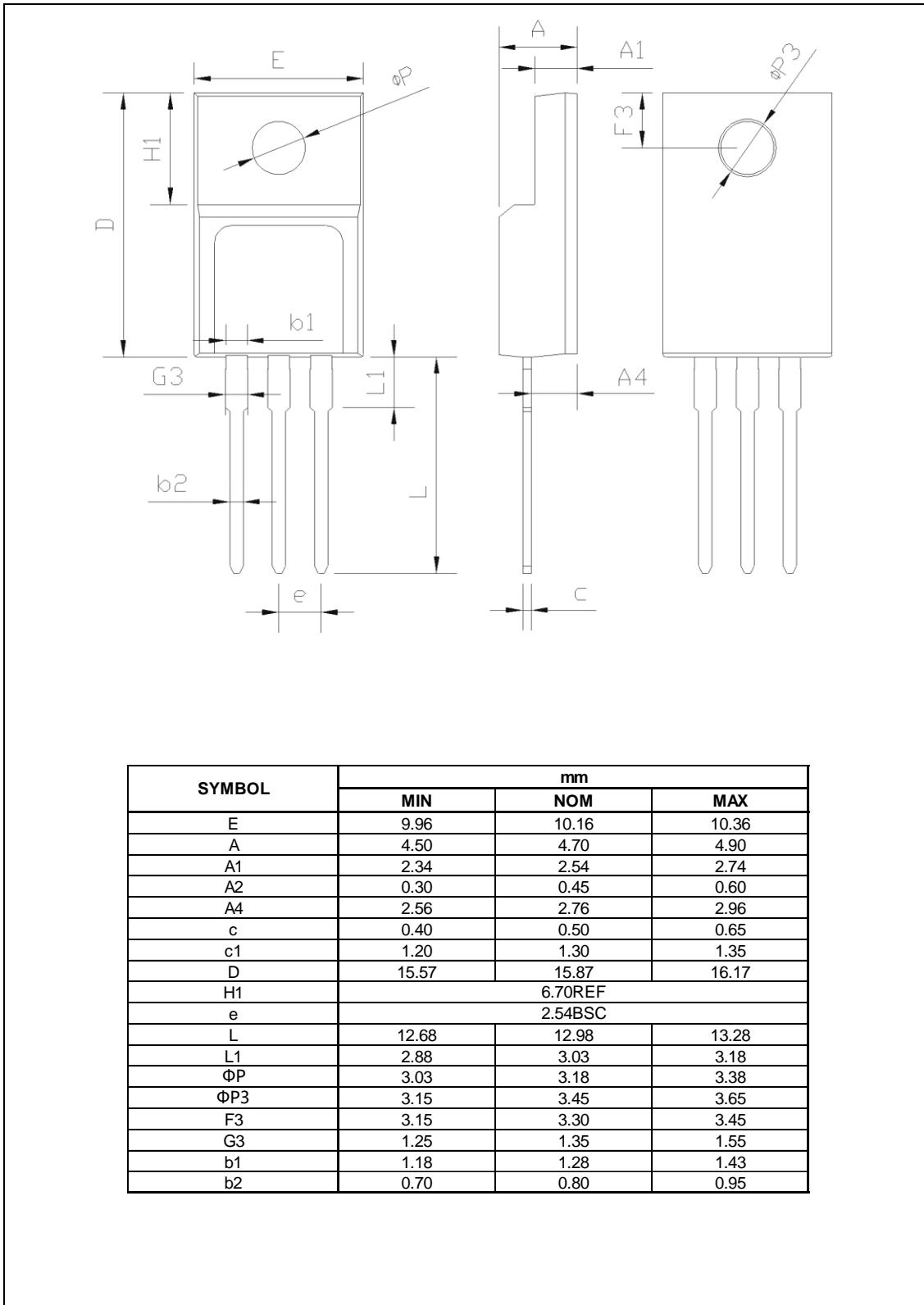
**■ Package Information**

Figure2, TO252 package outline dimension



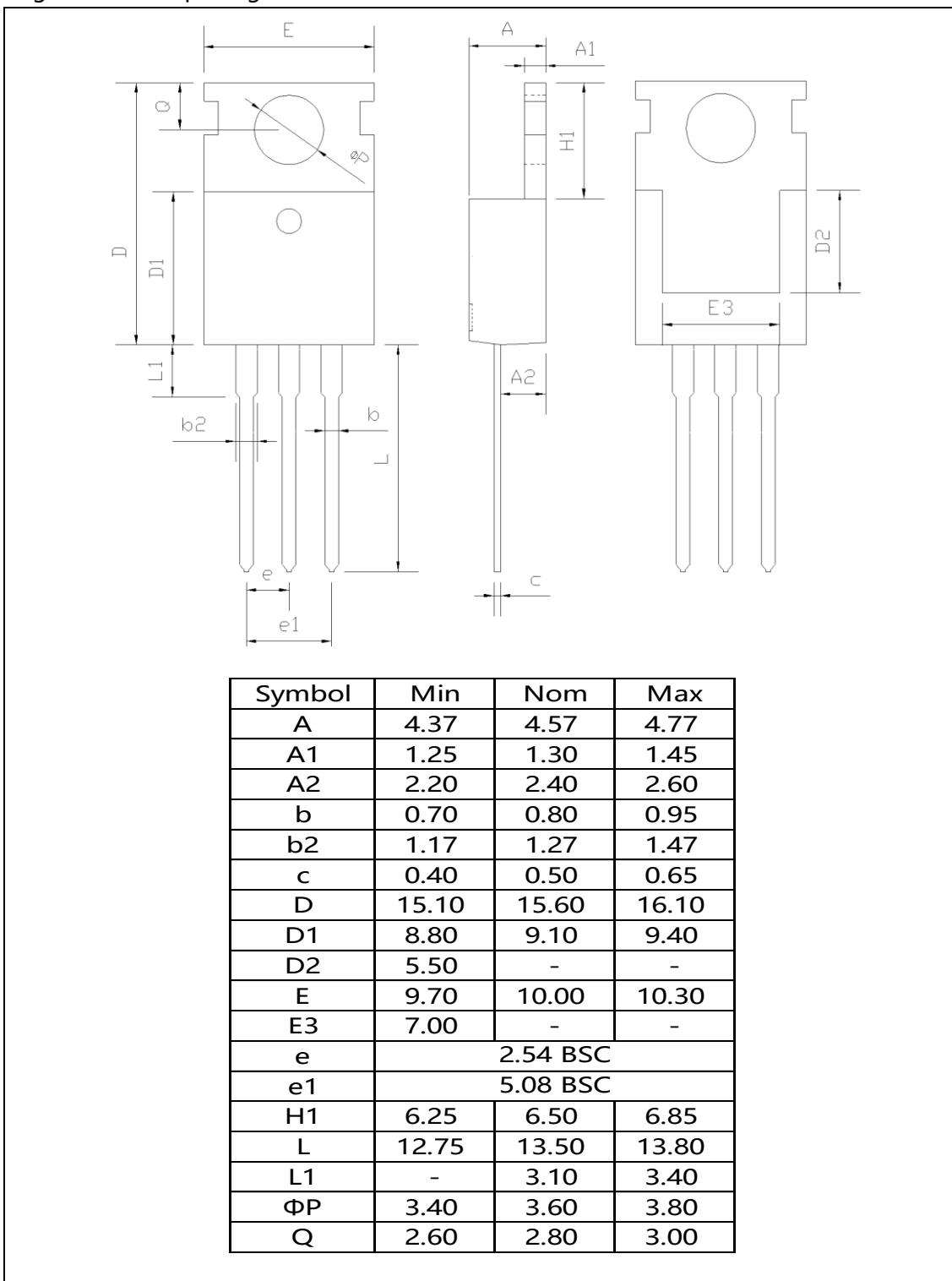
**■ Package Information**

Figure3, TO220F package outline dimension



**■ Package Information**

Figure4, TO220 package outline dimension



**■ Ordering Information**

Package	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO251	75	66	4950	6	29700
TO220F	50	20	1000	6	6000
TO220	50	20	1000	6	6000

Package	Units/Tape	Tapes/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO252	2500	2	5000	5	25000

■ Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG60R1K8AF	TO251	yes	yes	yes
OSG60R1K8DF	TO252	yes	yes	yes
OSG60R1K8FF	TO220F	yes	yes	yes
OSG60R1K8PF	TO220	yes	yes	yes